

How To Get autocad 2013 product key?The present invention generally relates to integrated circuit manufacturing and, more particularly, to a method and apparatus for manufacturing a semiconductor device including multi-material layers. In the manufacture of integrated circuits, a number of layers are deposited on semiconductor substrates, including both conductive and non-conductive layers. Each of the layers is etched to form features such as vias, trenches, metal lines, or other structure. A semiconductor device is often fabricated by forming multiple levels of metal, insulator and semiconductor on a semiconductor substrate. The resulting semiconductor device contains multiple metal layers separated by insulation layers. The metal layers on each level are connected to each other using vias or plugs. The metal layers are often connected to the substrate as well. Such connections are referred to as “bond-pads.” The metal layers are patterned using a series of masks and etches. Conventional metal layers, however, form only a single metal species. One problem is that the metal features on a given level cannot easily have different dimensions, whereas a design with varied metal feature sizes is desired for a number of reasons. For example, device function can vary based on the metal feature sizes. The different metal feature sizes also reduce chip size, which is desirable. More generally, the different metal feature sizes can allow the optimization of numerous parameters, including wiring density, device performance, and the like. Metal feature size can be controlled during the metal deposition process. However, the deposition parameters for features on a first level are not easily transferred to the deposition of features on a second level. Variations in the deposition parameters can cause variation in the composition and/or physical properties of the deposited metal, which can lead to problems for subsequent processing steps. A thin nickel layer is often included between two metal layers to reduce the diffusion of metal atoms between the metal layers. At the same time, the thin nickel layer provides

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